

SN54ALS191A, SN74ALS191A SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTERS

SDAS210C – DECEMBER 1982 – REVISED JULY 1996

- Single Down/Up Count-Control Line
- Look-Ahead Circuitry Enhances Speed of Cascaded Counters
- Fully Synchronous in Count Modes
- Asynchronously Presetable With Load Control
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

The 'ALS191A are synchronous 4-bit reversible up/down binary counters. Synchronous counting operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincidentally with each other when instructed by the steering logic. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters.

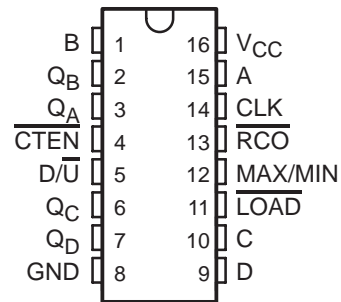
The outputs of the four flip-flops are triggered on a low-to-high-level transition of the clock (CLK) input if the count enable ($\overline{\text{CTEN}}$) input is low. A high at $\overline{\text{CTEN}}$ inhibits counting. The direction of the count is determined by the level of the down/up ($\overline{\text{D/U}}$) input. When $\overline{\text{D/U}}$ is low, the counter counts up, and when $\overline{\text{D/U}}$ is high, the counter counts down.

These counters feature a fully independent clock circuit. Changes at the control inputs ($\overline{\text{CTEN}}$ and $\overline{\text{D/U}}$) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter is dictated solely by the conditions meeting the stable setup and hold times.

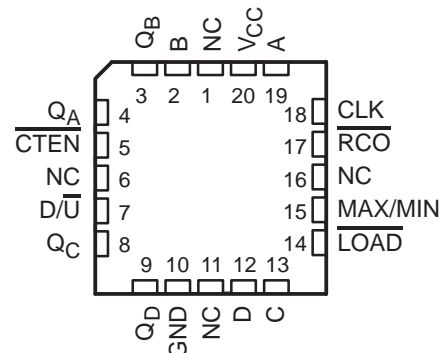
These counters are fully programmable. Each output can be preset to either level by placing a low on the $\overline{\text{LOAD}}$ input and entering the desired data at the data inputs. The output changes to agree with the data inputs independently of the level of the clock input. This feature allows the counters to be used as modulo-N dividers by simply modifying the count length with the preset inputs.

CLK, $\overline{\text{D/U}}$, and $\overline{\text{LOAD}}$ are buffered to lower the drive requirement, which significantly reduces the loading on (current required by) clock drivers, for long parallel words.

SN54ALS191A . . . J PACKAGE
SN74ALS191A . . . D OR N PACKAGE
(TOP VIEW)



SN54ALS191A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

Copyright © 1996, Texas Instruments Incorporated

SN54ALS191A, SN74ALS191A SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTERS

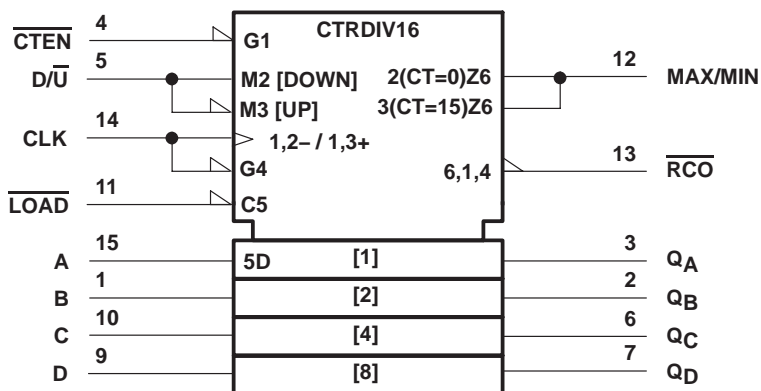
SDAS210C – DECEMBER 1982 – REVISED JULY 1996

description (continued)

Two outputs are available to perform the cascading function: ripple clock and maximum/minimum count. The latter output produces a high-level output pulse with a duration approximately equal to one complete cycle of the clock while the count is minimum (0) counting down or maximum (15) counting up. The ripple-clock output (\overline{RCO}) produces a low-level output pulse under those same conditions, but only while the clock input is low. The counter easily can be cascaded by feeding the ripple-clock output to the enable input of the succeeding counter if parallel clocking is used, or to the clock input if parallel enabling is used. The maximum/minimum count (MAX/MIN) output can be used to accomplish look ahead for high-speed operation.

The SN54ALS191A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS191A is characterized for operation from 0°C to 70°C .

logic symbol†

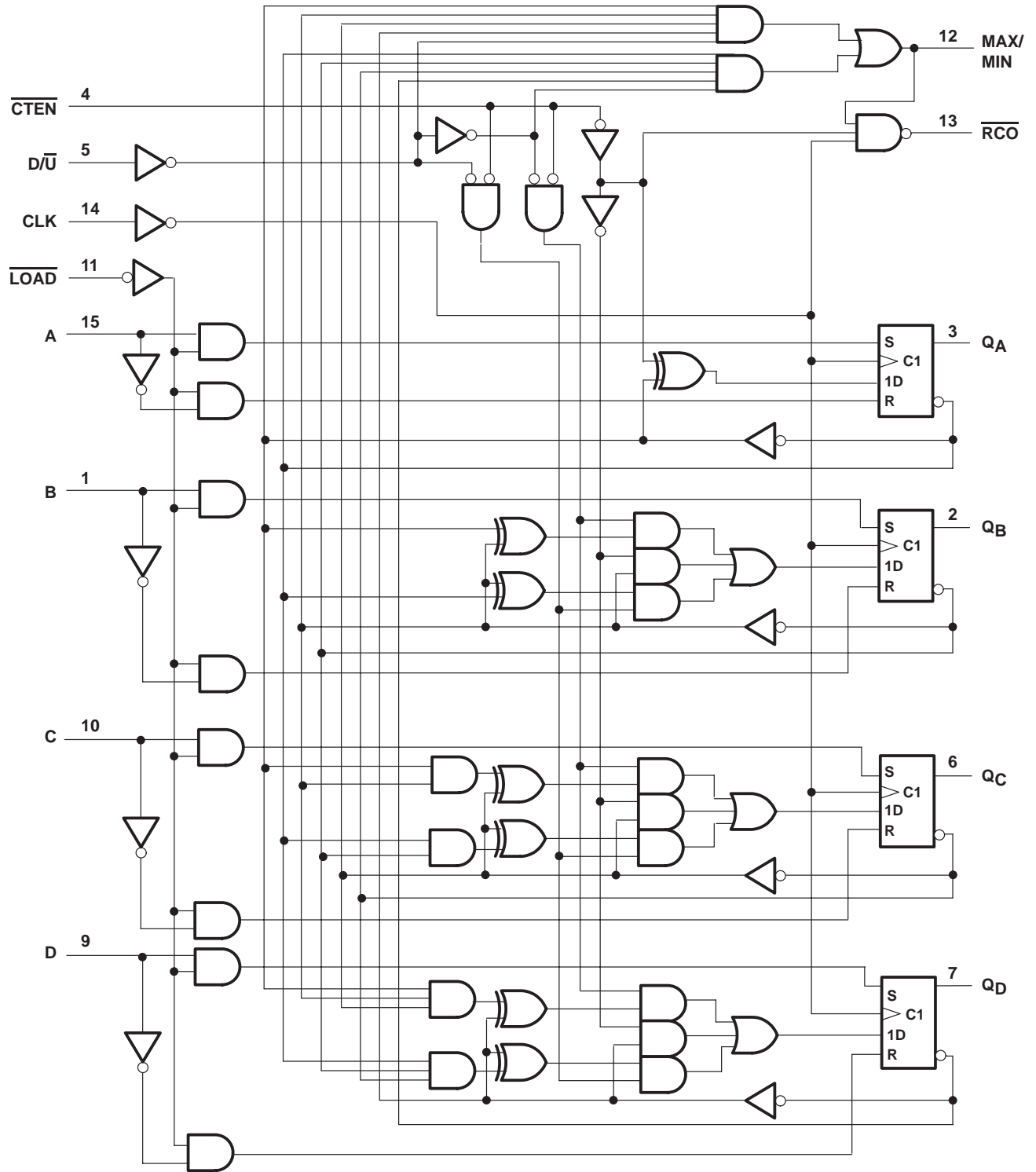


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

SN54ALS191A, SN74ALS191A SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTERS

SDAS210C – DECEMBER 1982 – REVISED JULY 1996

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



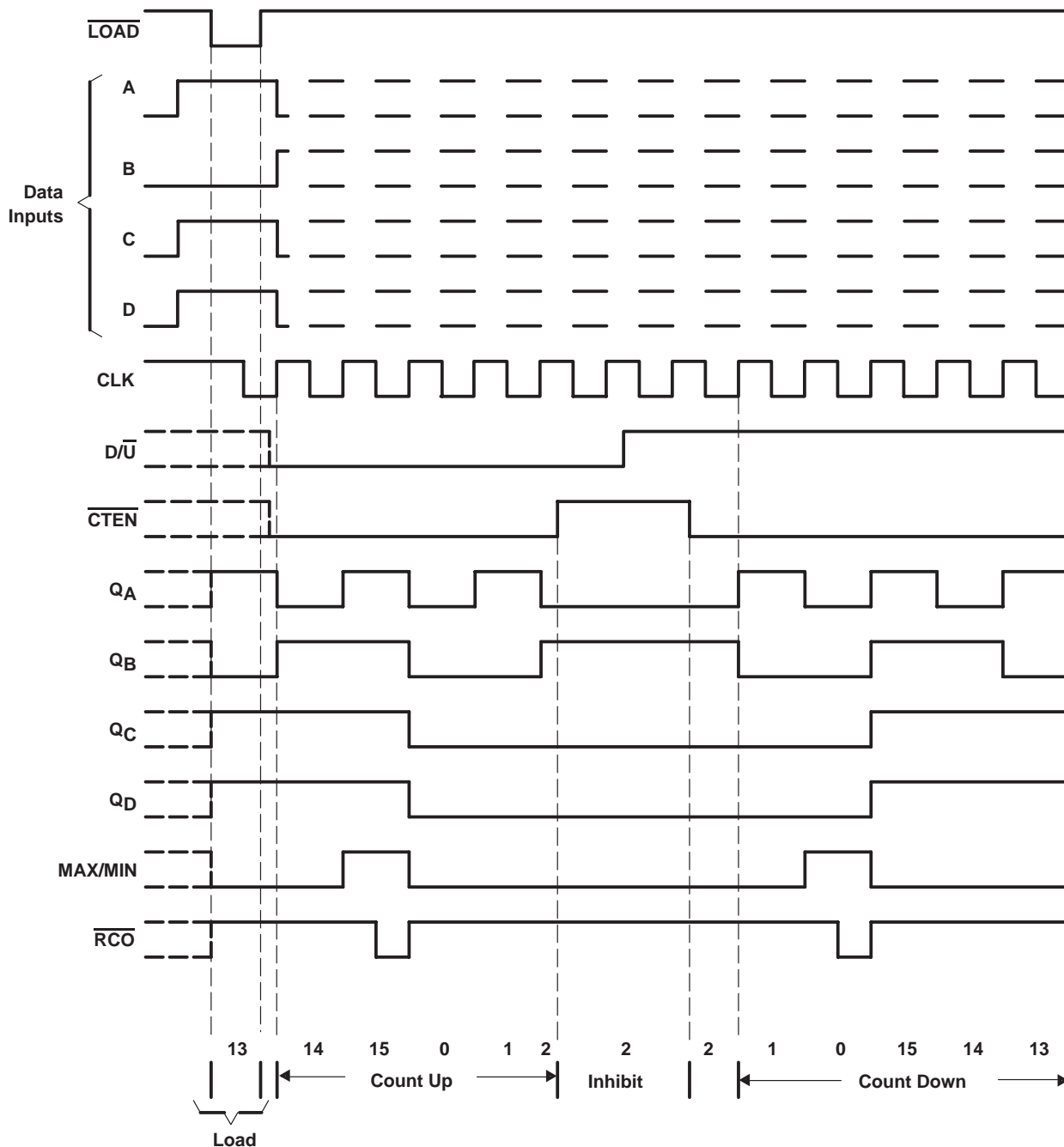
SN54ALS191A, SN74ALS191A SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTERS

SDAS210C – DECEMBER 1982 – REVISED JULY 1996

typical load, count, and inhibit sequences

The following sequence is illustrated below:

1. Load (preset) to binary 13
2. Count up to 14, 15 (maximum), 0, 1, and 2
3. Inhibit
4. Count down to 1, 0 (minimum), 15, 14, and 13



SN54ALS191A, SN74ALS191A SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTERS

SDAS210C – DECEMBER 1982 – REVISED JULY 1996

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A : SN54ALS191A	–55°C to 125°C
SN74ALS191A	0°C to 70°C
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS191A			SN74ALS191A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			–0.4			–0.4	mA
I_{OL}	Low-level output current			4			8	mA
f_{clock}	Clock frequency	0		20	0		30	MHz
t_w	Pulse duration	CLK high or low		20	16.5		ns	
		LOAD low		25	20			
t_{su}	Setup time	Data before $\overline{LOAD}\uparrow$		25	20		ns	
		\overline{CTEN} before $CLK\uparrow$		45	20			
		D/\overline{U} before $CLK\uparrow$		30	20			
		\overline{LOAD} inactive before $CLK\uparrow$		20	20			
t_h	Hold time	Data after $\overline{LOAD}\uparrow$		5	5		ns	
		\overline{CTEN} after $CLK\uparrow$		0	0			
		D/\overline{U} after $CLK\uparrow$		0	0			
T_A	Operating free-air temperature	–55		125	0		70	°C



SN54ALS191A, SN74ALS191A SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTERS

SDAS210C – DECEMBER 1982 – REVISED JULY 1996

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS191A		SN74ALS191A		UNIT
			MIN	TYP†	MAX	MIN	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA		-1.5		-1.5		V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -0.4 mA		V _{CC} - 2		V _{CC} - 2		V
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 4 mA	0.25	0.4	0.25	0.4	
		I _{OL} = 8 mA			0.35	0.5	
I _I	V _{CC} = 5.5 V, V _I = 7 V		0.2		0.1		mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V		20		20		μA
I _{IL}	CTEN or CLK	V _{CC} = 5.5 V, V _I = 0.4 V	-0.2		-0.2		mA
	All others		-0.2		-0.1		
I _O ‡	V _{CC} = 5.5 V, V _O = 2.25 V		-20	-112	-30	-112	mA
I _{CC}	V _{CC} = 5.5 V, All inputs at 0		12	22	12	22	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (OUTPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX§				UNIT
			SN54ALS191A		SN74ALS191A		
			MIN	MAX	MIN	MAX	
f _{max}			20		30	MHz	
t _{PLH}	LOAD	Any Q	7	37	7	30	ns
t _{PHL}			8	34	8	30	
t _{PLH}	A, B, C, D	Any Q	3	25	3	21	ns
t _{PHL}			4	25	4	21	
t _{PLH}	CLK	RCO	5	24	5	20	ns
t _{PHL}			5	25	5	20	
t _{PLH}	CLK	Any Q	3	26	3	18	ns
t _{PHL}			3	22	3	18	
t _{PLH}	CLK	MAX/MIN	8	37	8	31	ns
t _{PHL}			8	34	8	31	
t _{PLH}	D \bar{U}	RCO	8	45	8	37	ns
t _{PHL}			10	36	10	28	
t _{PLH}	D \bar{U}	MAX/MIN	8	35	8	25	ns
t _{PHL}			8	30	8	25	
t _{PLH}	CTEN	RCO	4	21	4	18	ns
t _{PHL}			4	23	4	18	

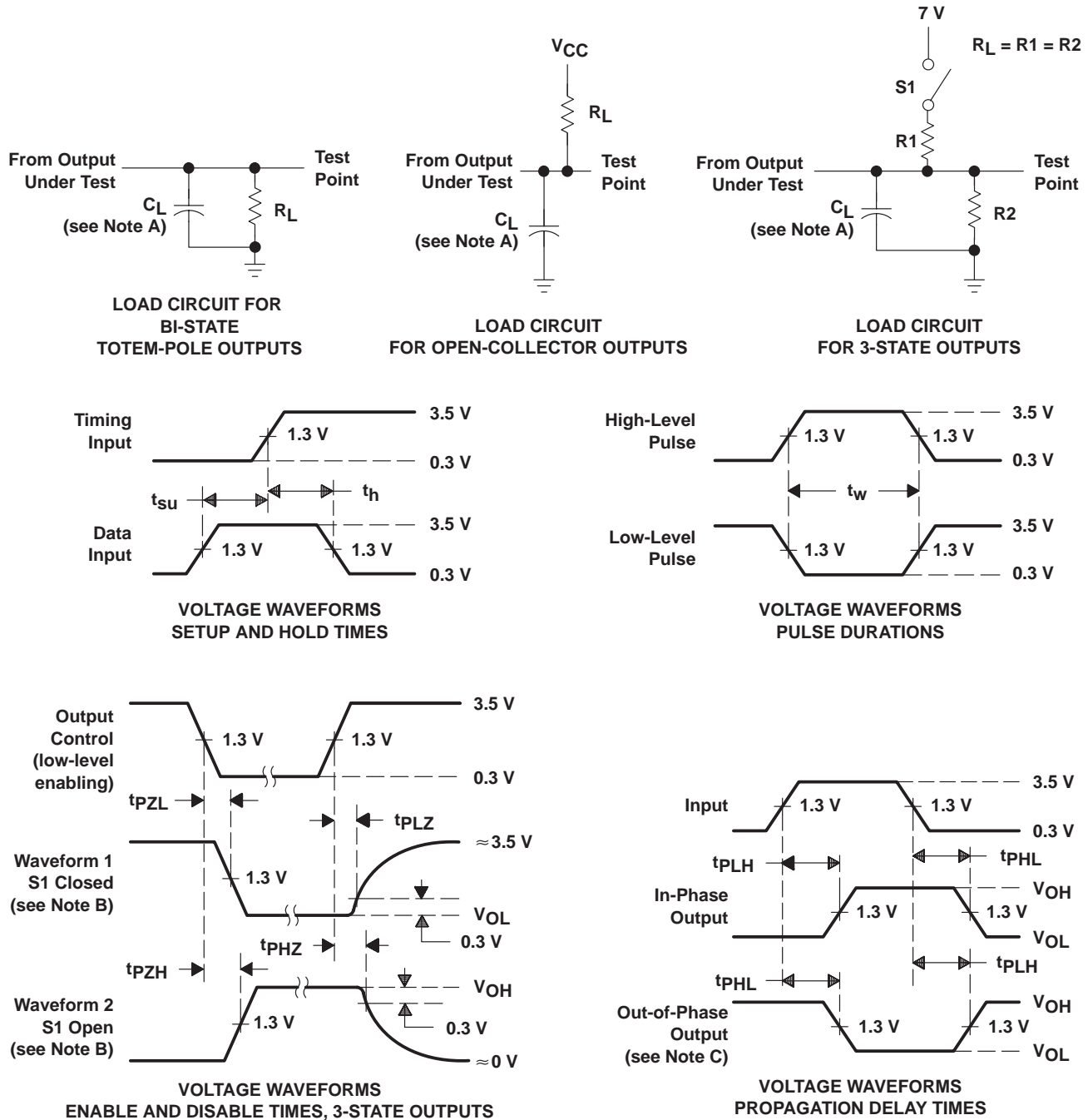
§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54ALS191A, SN74ALS191A SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTERS

SDAS210C – DECEMBER 1982 – REVISED JULY 1996

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86840012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86840012A SNJ54ALS 191AFK	Samples
5962-8684001EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684001EA SNJ54ALS191AJ	Samples
5962-8684001FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684001FA SNJ54ALS191AW	Samples
SN54ALS191AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS191AJ	Samples
SN74ALS191AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS191A	Samples
SN74ALS191ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS191A	Samples
SN74ALS191ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS191A	Samples
SN74ALS191AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS191AN	Samples
SN74ALS191ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS191AN	Samples
SNJ54ALS191AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86840012A SNJ54ALS 191AFK	Samples
SNJ54ALS191AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684001EA SNJ54ALS191AJ	Samples
SNJ54ALS191AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684001FA SNJ54ALS191AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS191A, SN74ALS191A :

● Catalog: [SN74ALS191A](#)

● Military: [SN54ALS191A](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS191ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS191ADR	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16

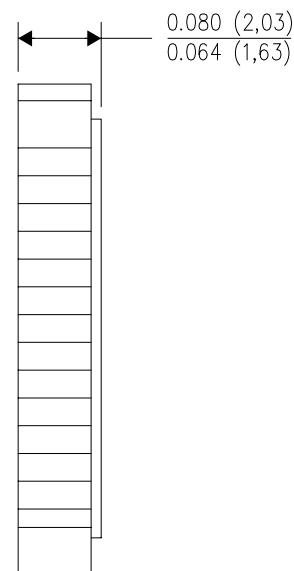
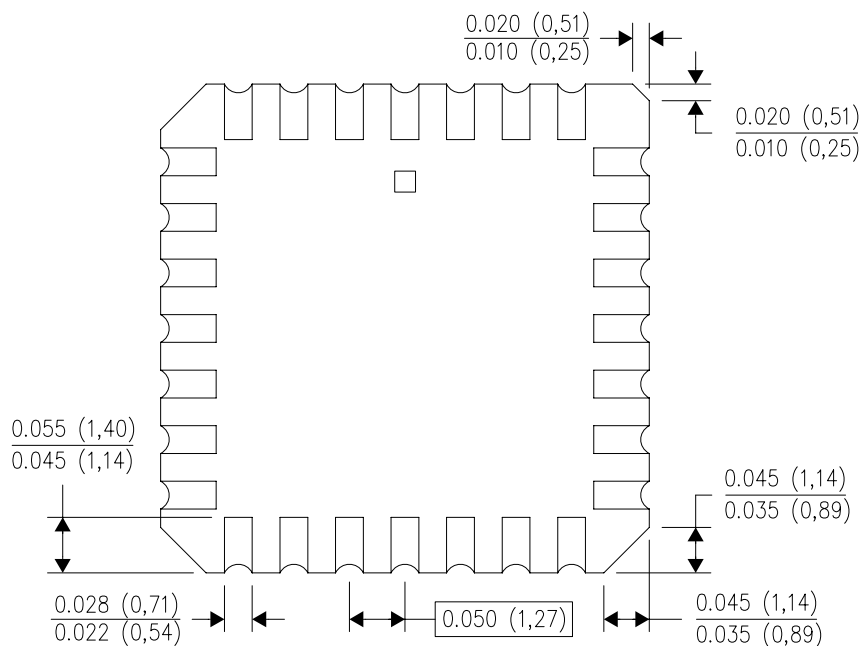
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com